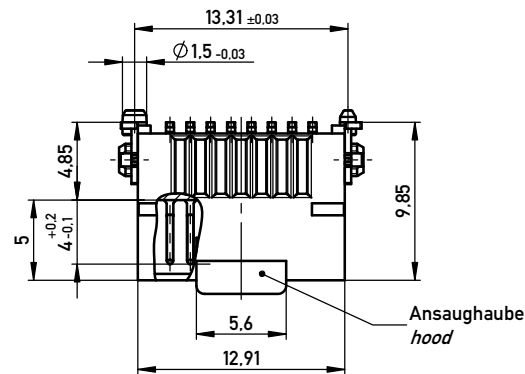
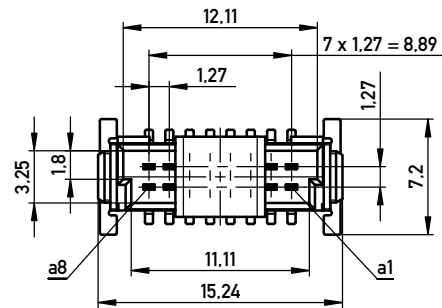
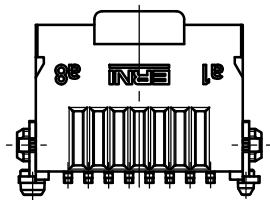
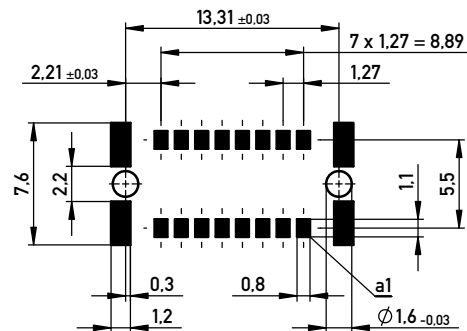


Leiterplatten-Layout Vorschlag für SMT PCB-Layout Proposal for SMT



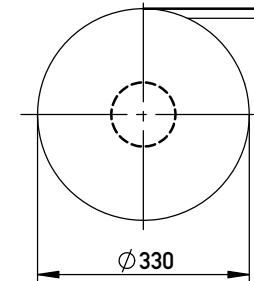
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

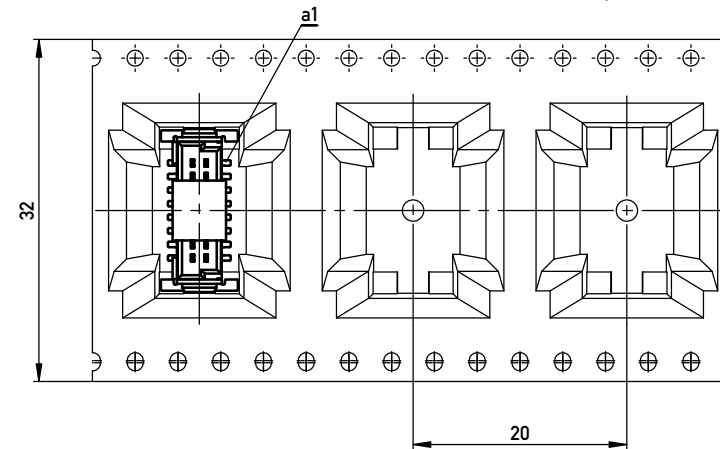
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0.1 mm

Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 250 Stück
Packaging unit: 250 pcs



Abspulrichtung - Reel off Direction



BA 8-23 - hohe Bauhöhe
type 8-23 - High Profile

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Information:				Tolerances		 All Dimensions in mm		Scale 3:1			
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								Messerl. SMC-Q 16-SMD-BA8-23 <i>Male SMC-Q 16-SMD-type8-23</i>			
				ERNI				www.ERNI.com			
e		26.06.2015						I			
Index		Date						A3			
								Class SMCQ			

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